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(54) **INTEGRATED CIRCUIT INTERCONNECTS WITH COAXIAL CONDUCTORS**

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**H01R 12/00** (2006.01)

(52) **U.S. Cl.** ..... **439/66**

(58) **Field of Classification Search** ..... 439/65, 439/66; 438/106, 618, 622, 667  
See application file for complete search history.

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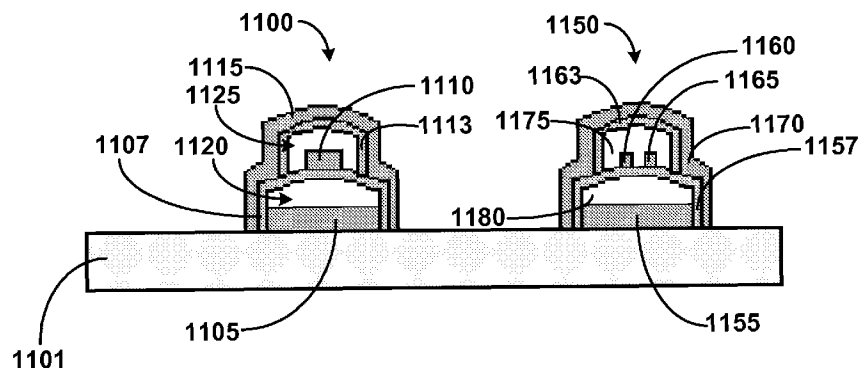
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(57) **ABSTRACT**

High performance interconnect devices, structures, and fabrication methods are provided herein. According to some embodiments of the present invention, an interconnect device used to connect components or route signals in an integrated circuit can comprise multiple conductors. A first conductor of the interconnect device can define a first conductor axis, and a second conductor of the interconnect device can define a second conductor axis. The second conductor can be proximate the first conductor such that first conductor axis is substantially coaxially situated relative to the second conductor axis to provide a high performance interconnect having a coaxial alignment. The first conductor and the second conductor can define a gap disposed between and separating the conductors. Other embodiments are also claimed and described.

**15 Claims, 9 Drawing Sheets**



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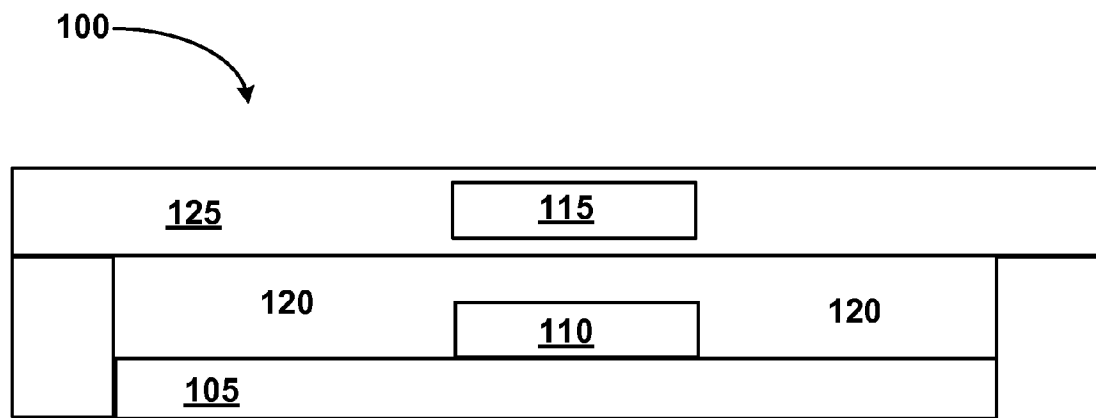
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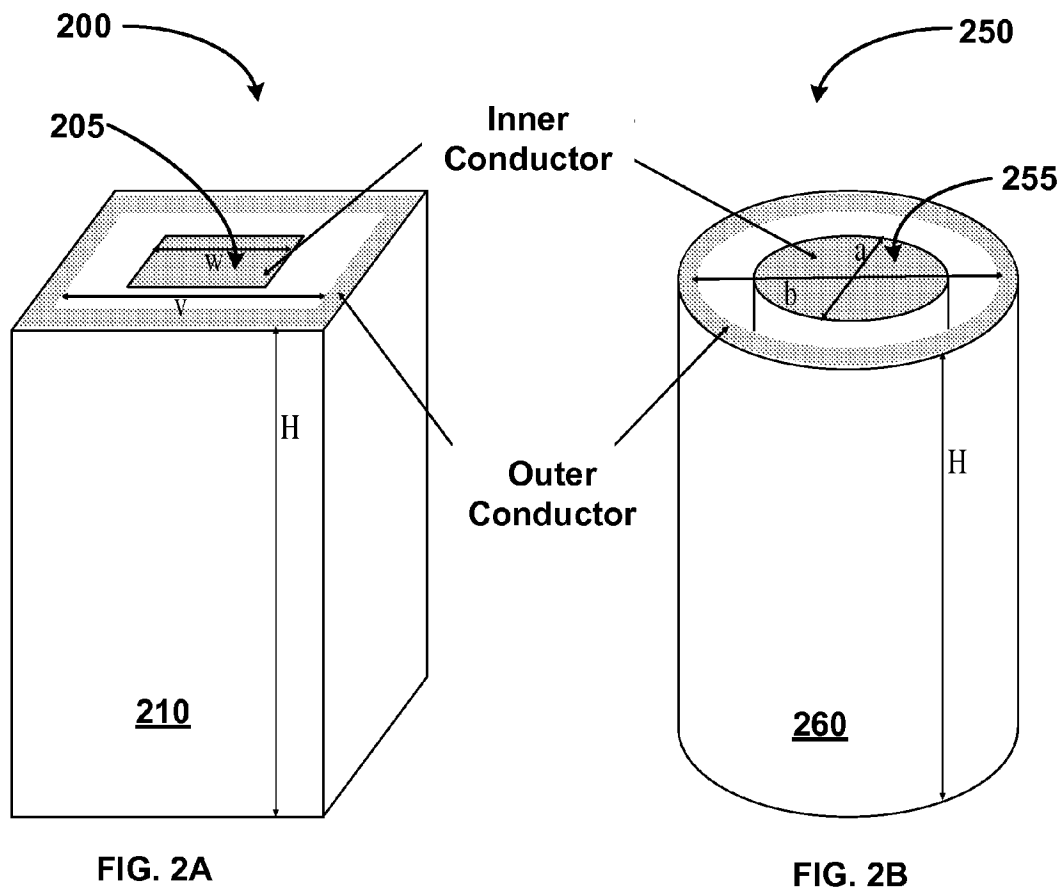
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**FIG. 1**



**FIG. 2A**

**FIG. 2B**

**FIG. 2**

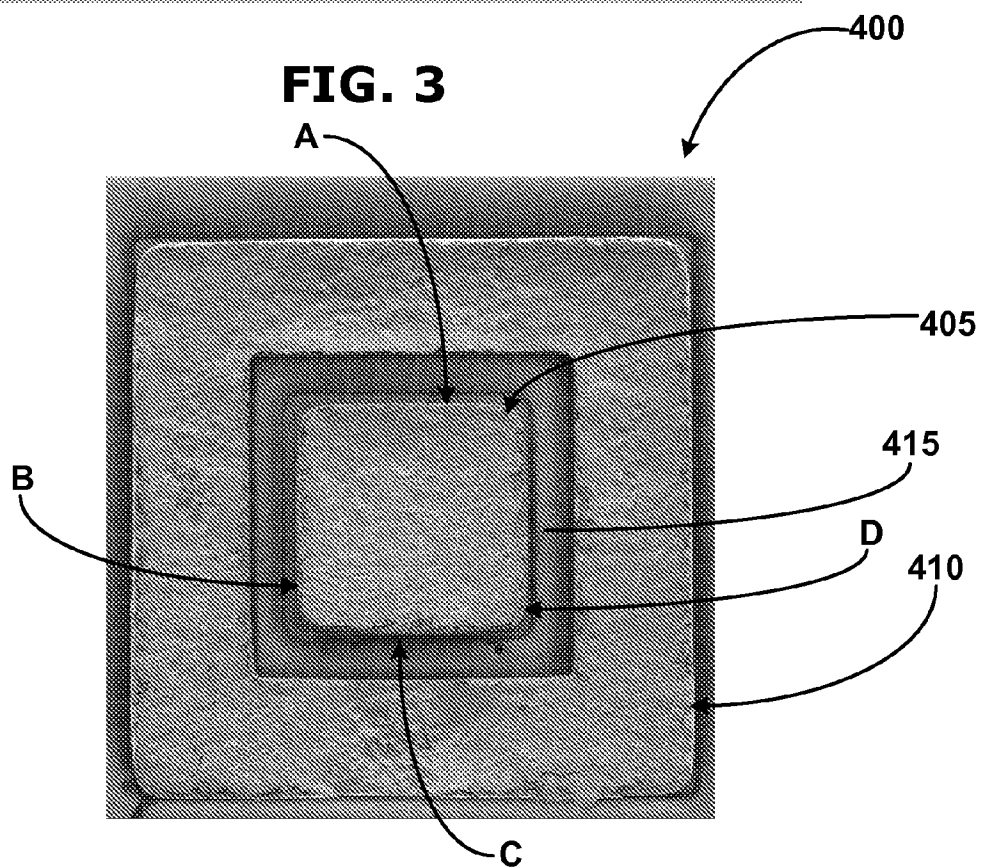
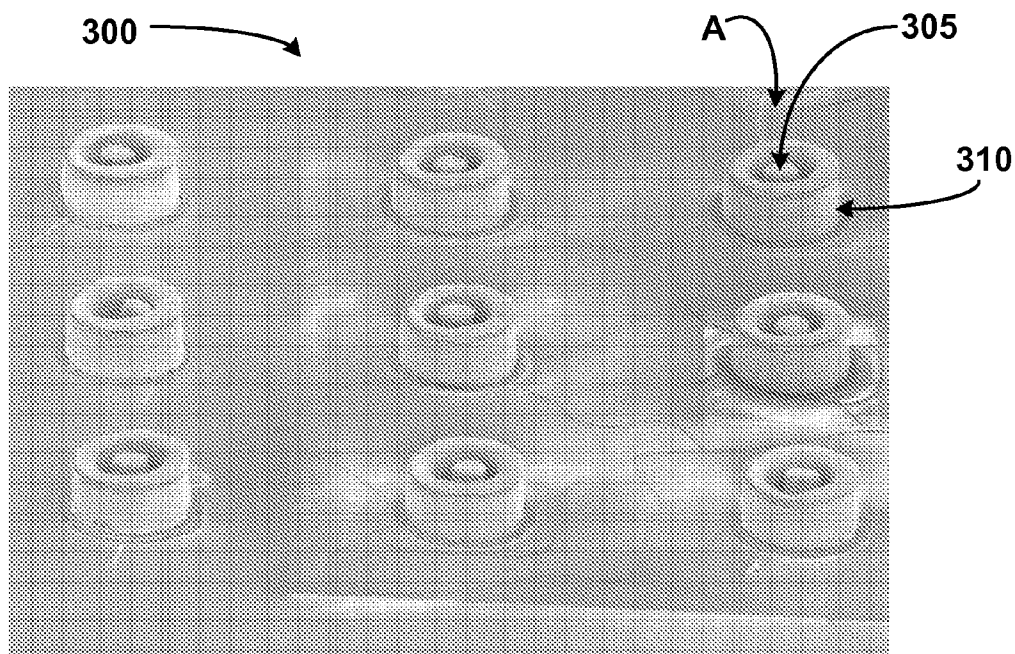
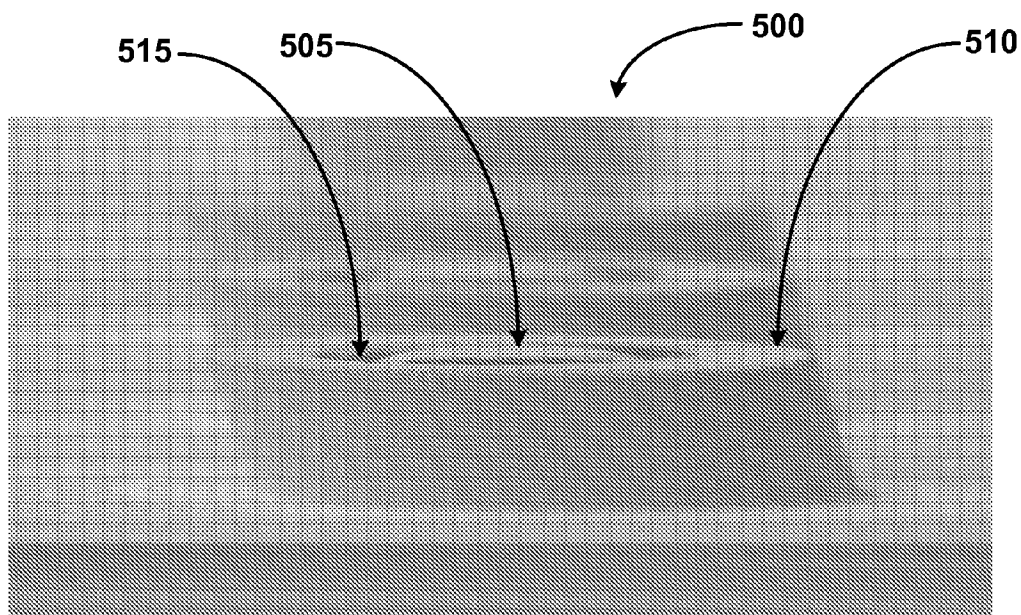
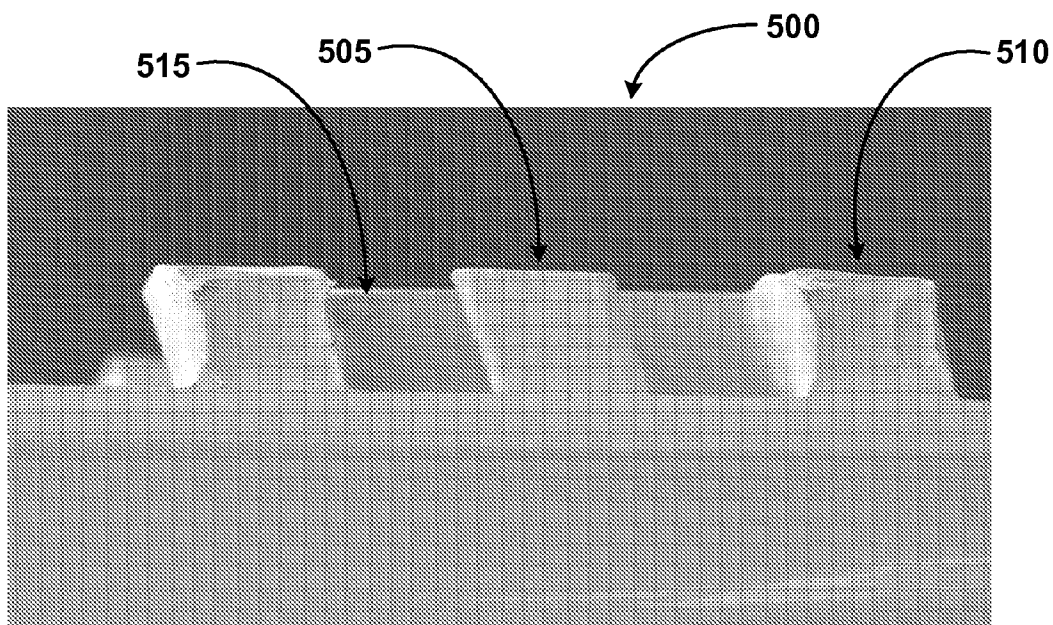


FIG. 4



**FIG. 5**



**FIG. 6**

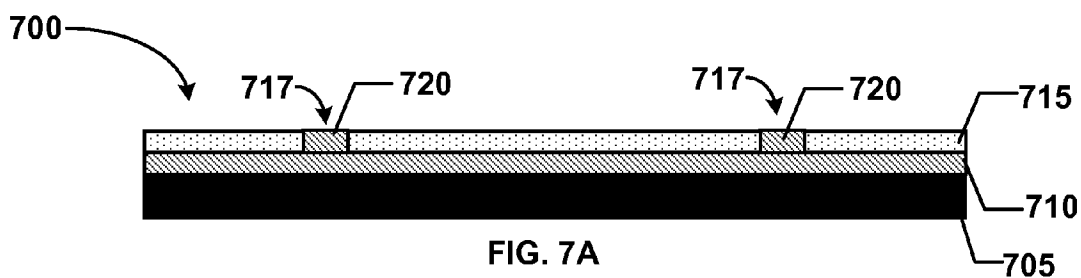


FIG. 7A

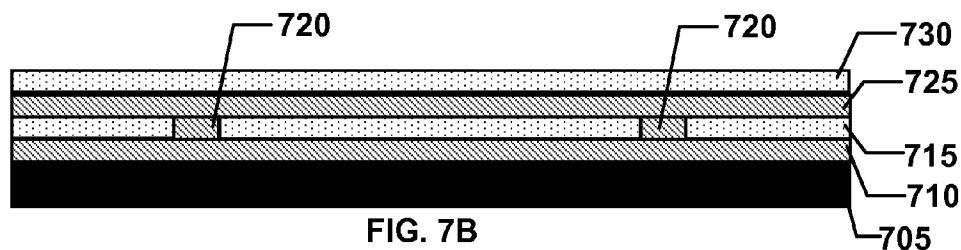


FIG. 7B

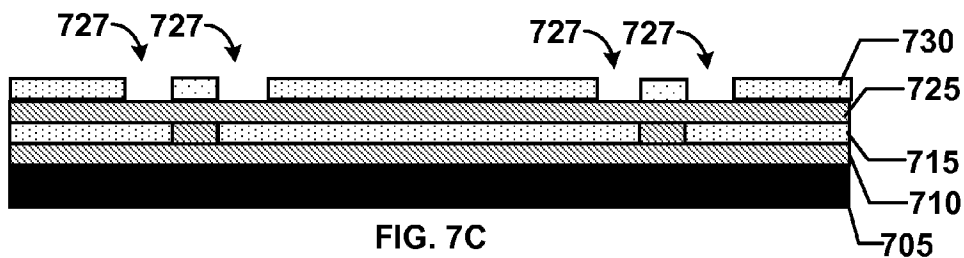


FIG. 7C

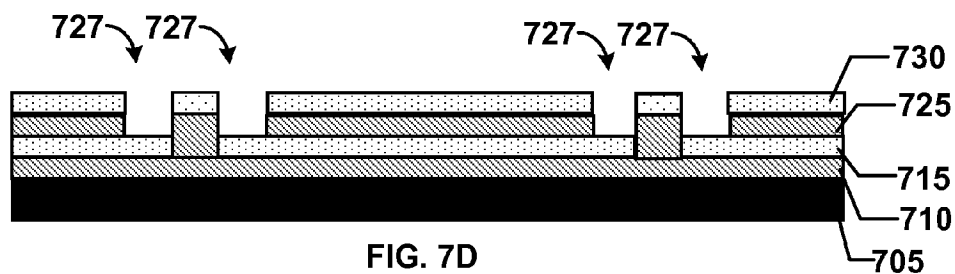


FIG. 7D

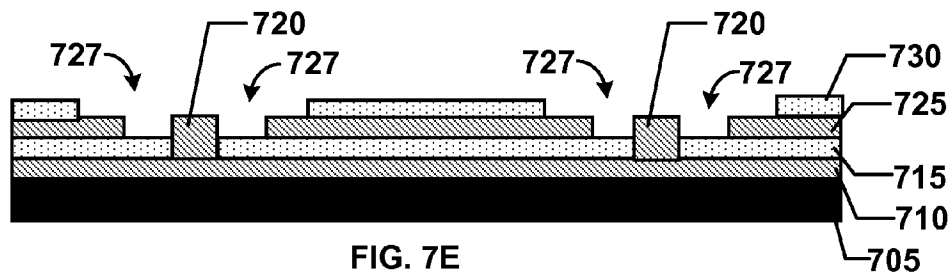


FIG. 7E

FIG. 7

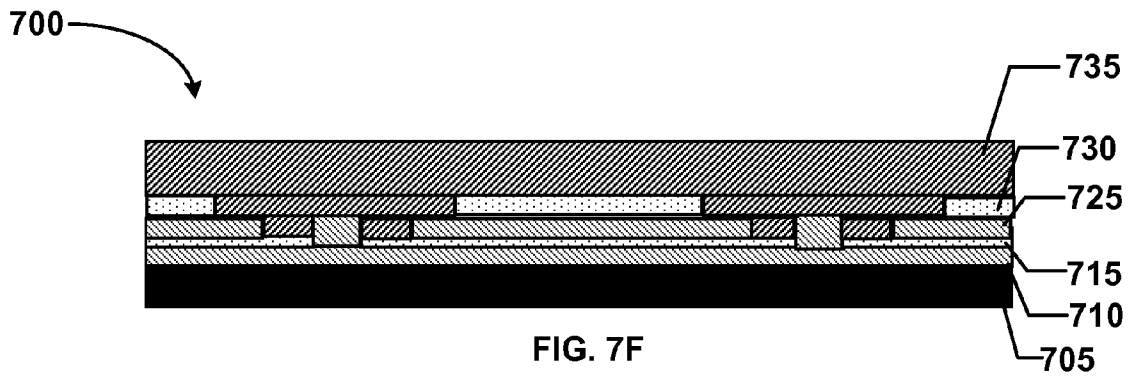


FIG. 7F

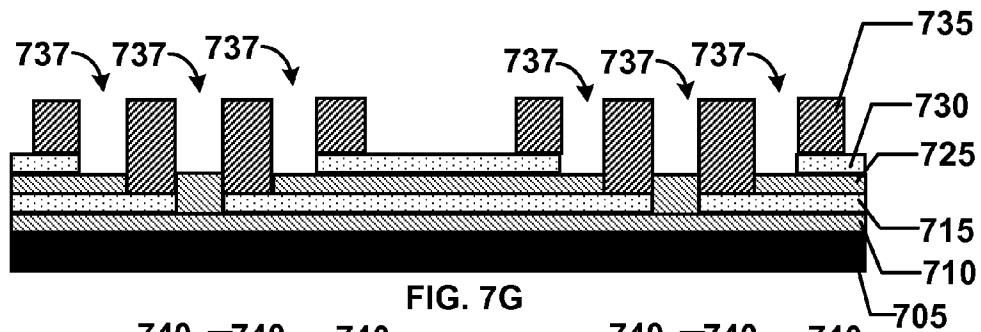


FIG. 7G

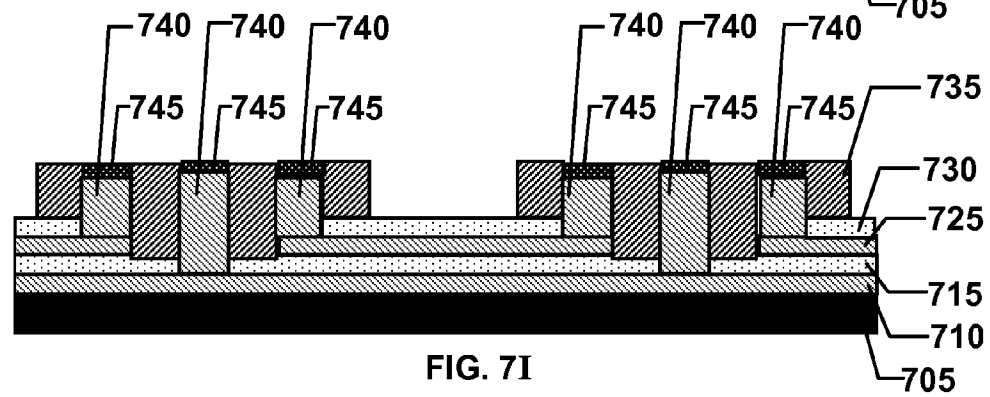


FIG. 7I

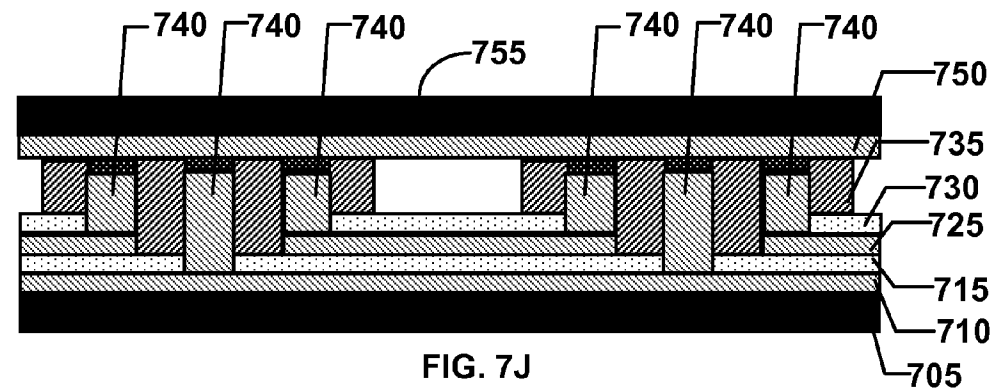
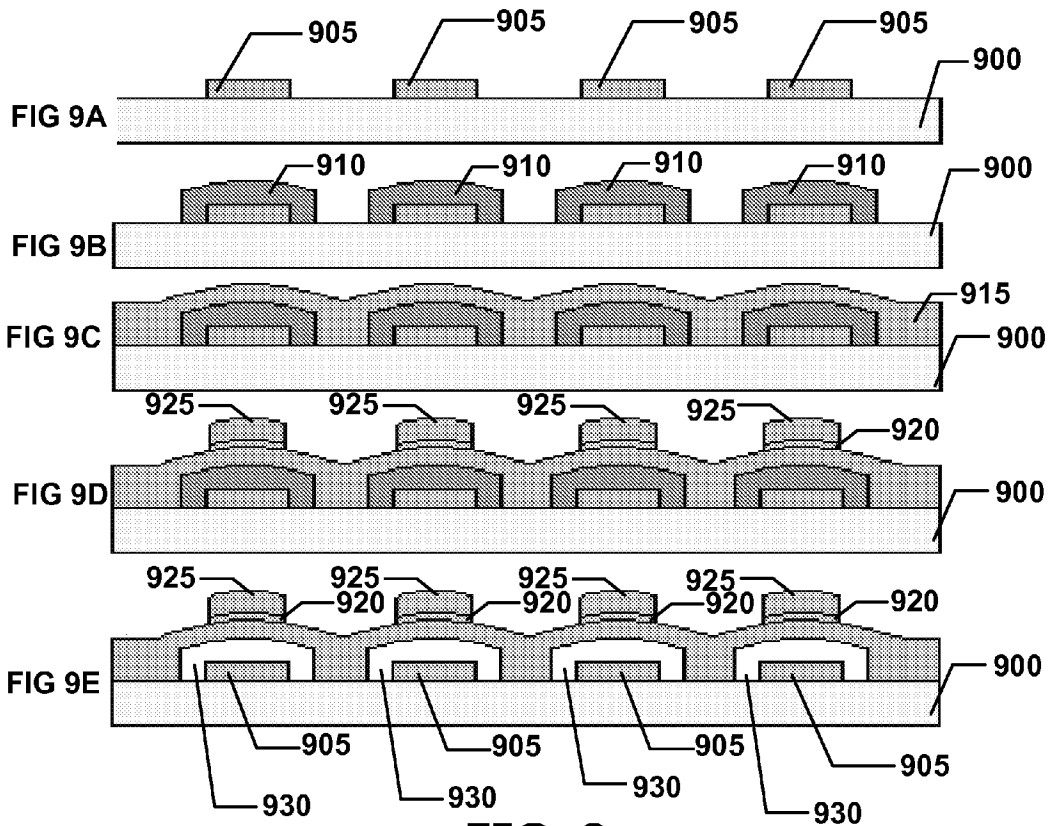
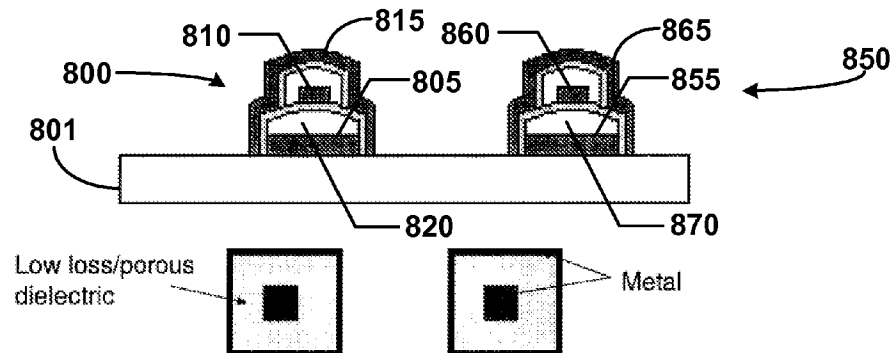


FIG. 7J

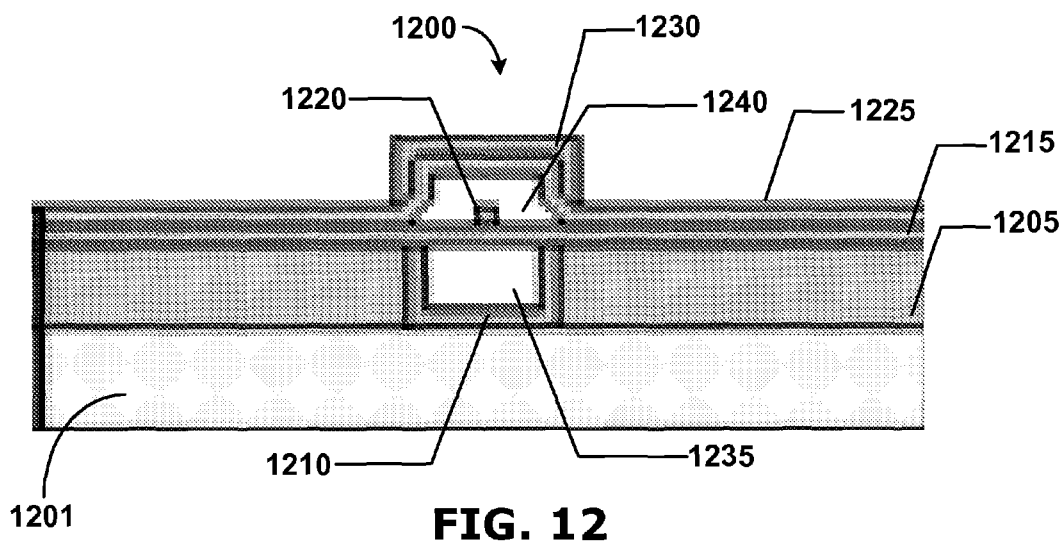
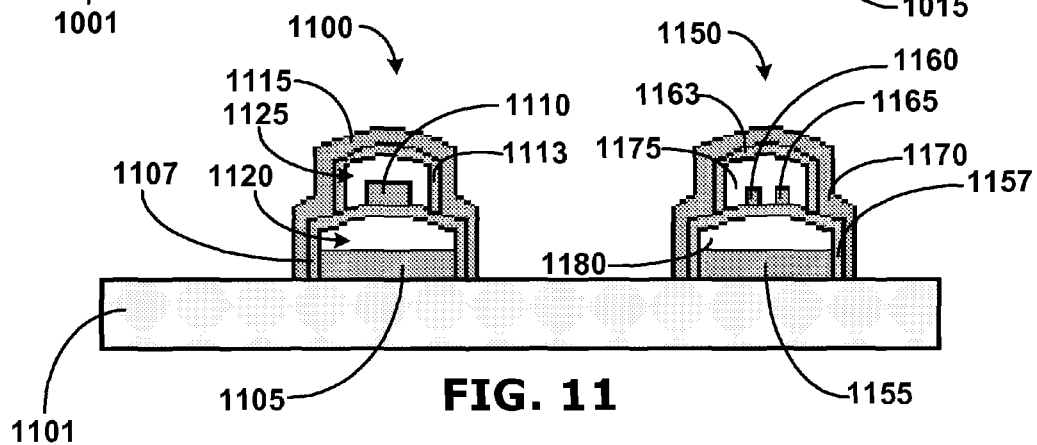
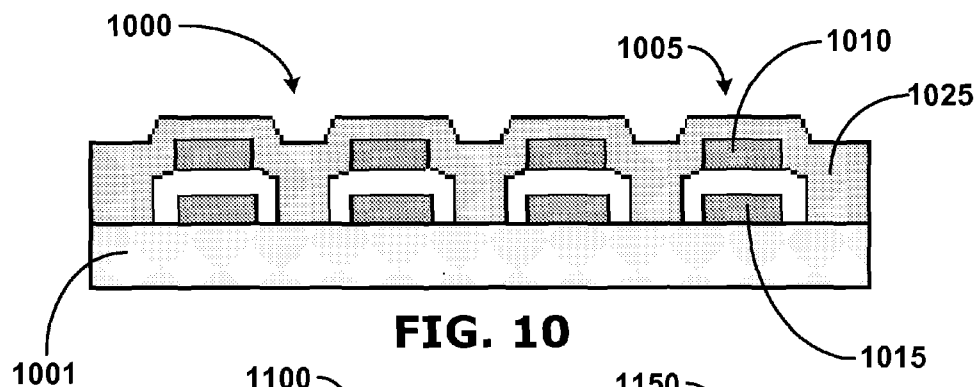
FIG. 7

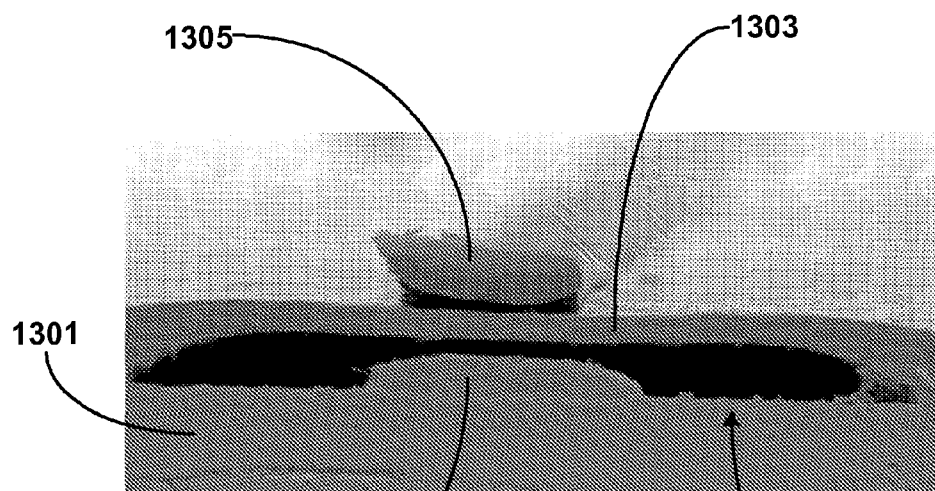
**FIG. 8**



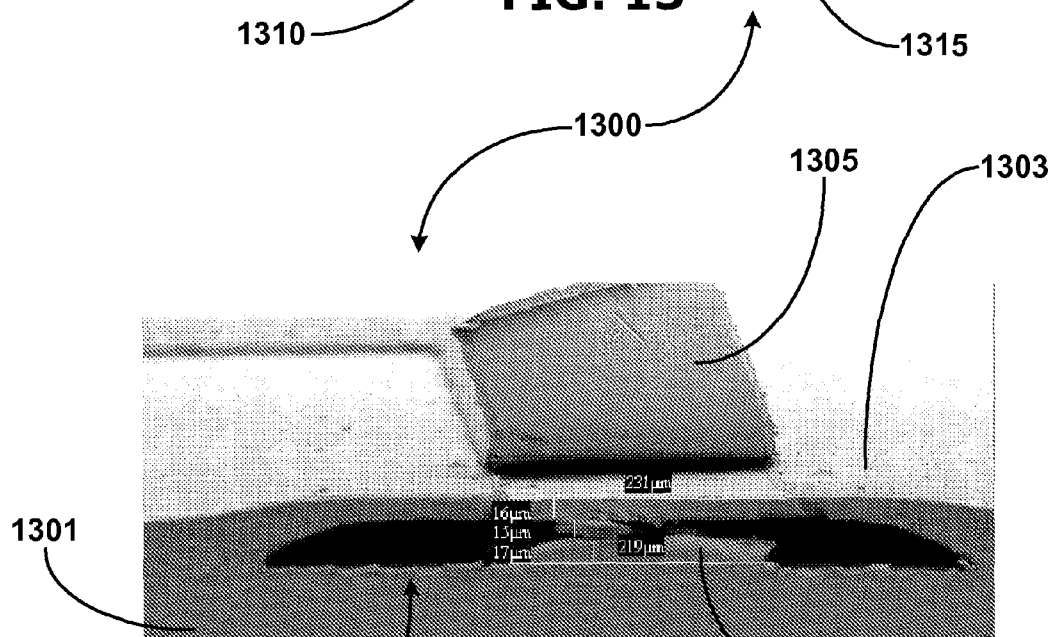
**FIG. 9**







**FIG. 13**



**FIG. 14**

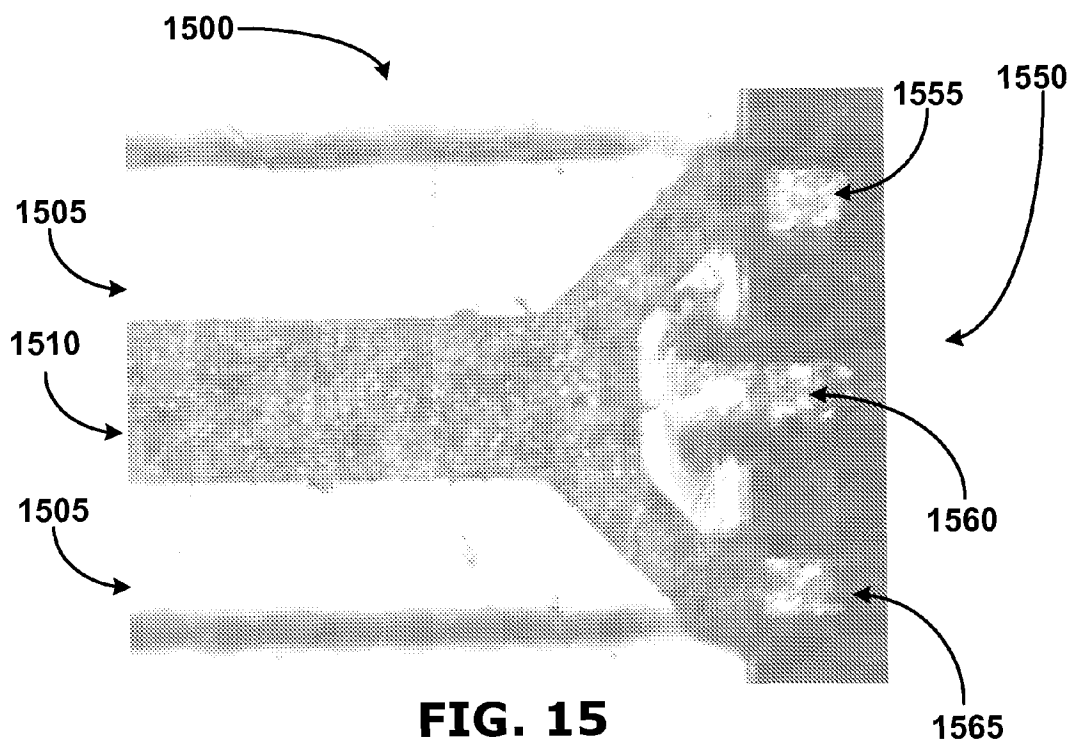


FIG. 15

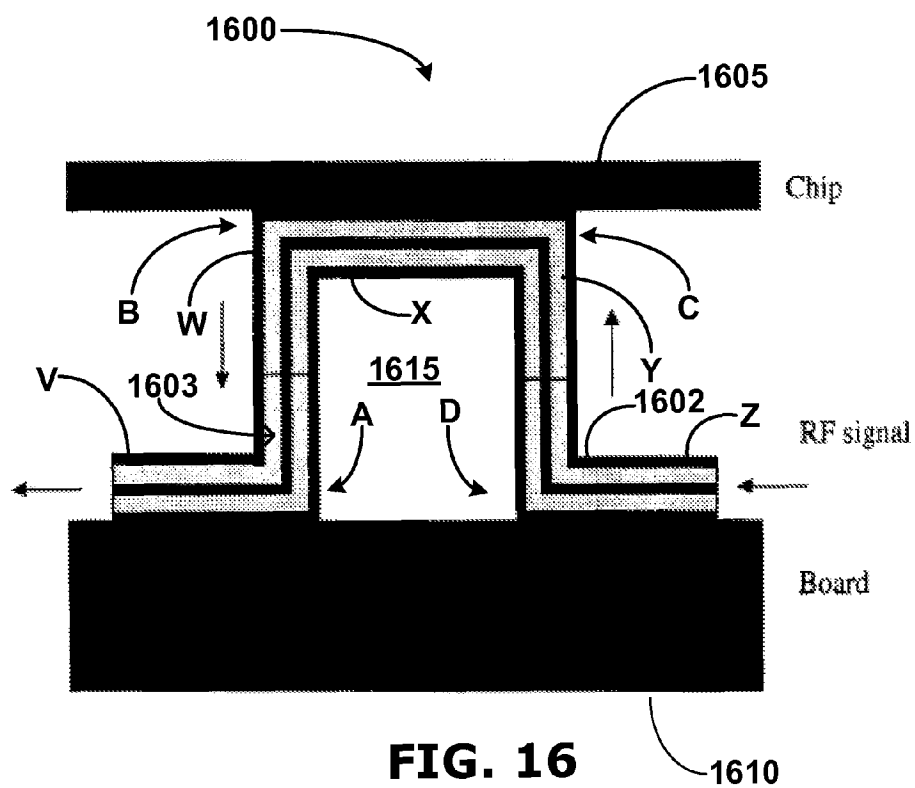


FIG. 16

# INTEGRATED CIRCUIT INTERCONNECTS WITH COAXIAL CONDUCTORS

## CROSS-REFERENCE TO RELATED APPLICATION

The present application claims priority to and the benefit of U.S. Provisional Patent Application No. 60/733,818, filed 4 Nov. 2005, and entitled "High Performance Interconnect For Boards, Chips, and Chip-to Board Connections", which is hereby incorporated by reference in its entirety as if fully set forth below.

## TECHNICAL FIELD

The various embodiments of the present invention relate generally to integrated circuit interconnect devices, and more particularly, to high performance interconnect devices and structures that can be integrated circuit transmission lines or connect components, and fabrication methods for making such devices and structures.

## BACKGROUND

The demands for ever-increasing bandwidths in digital data communication equipment at reduced power consumption lever equipment are constantly growing. These demands not only require more efficient integrated circuit components, but also higher performance interconnect structures and devices and chip-to-substrate connections. Indeed, as one example, the International Technology Roadmap for Semiconductors (ITRS) projects that high performance chips in the very near future will have operating frequencies, both on-chip and off-chip (i.e., chip to substrate), rising above 50 GHz.

This dramatic increase in operating frequencies will require improvements over conventional integrated circuit interconnect structures and fabrication methods. As an example, current interconnect devices are not capable of enabling such high operating frequencies, thus high performance interconnect devices and structures will be needed to support high operational frequencies. In addition, cost-effective fabrication methods to produce high performance interconnect devices and structures will also be needed to provide high performance integrated circuit chips and packages. Some of the challenges in achieving high-bandwidth communication using electrical interconnects include high losses in the substrate dielectric, reflections and impedance discontinuities, and susceptibility to cross-talk.

Accordingly, there is a need for high performance interconnect device, structures, and associated fabrication methods that provide simple fabrication methods to produce interconnects having improved properties with fewer process steps and reduced costs. In addition, there is a need for improved on-chip and off-chip interconnect devices and associated fabrication methods to enable and support increased data throughput. It is to the provision of such interconnects and fabrication methods that the various embodiments of the present invention are directed.

## BRIEF SUMMARY

Various embodiments of the present invention are directed to high performance interconnect devices and structures. Some embodiments are also directed to methods to fabricated high performance interconnect devices and structures. When discussing the various embodiments of the present invention

herein, reference is sometimes made to interconnects, interconnect structures, interconnect devices, and transmission lines; and at times these terms are used interchangeably.

Also as discussed in more detail below certain embodiments of the present invention can be implemented as on-chip interconnects (or transmission lines) and other embodiments can be implemented as off-chip interconnects. As used herein, on-chip interconnects can be used to connect certain points or areas on a chip and off-chip interconnects can be used to connect multiple components such as an integrated chip and associated substrate. Also, embodiments of the present invention can serve as high performance interfaces between components. The various embodiments of the present invention can be fabricated using certain build up process as well as imprinting techniques.

Broadly described, an interconnection device according an embodiment of the present invention can comprise a first conductor and a second conductor. The second conductor can be disposed proximate the first conductor and also be substantially coaxially situated to the second conductor. The first conductor and the second conductor can define a gap between each other. The gap can comprise a gas so that the gas clads the first conductor. The gap can have a thickness ranging from approximately 10 micrometers to approximately 1 millimeter. Also, a polymer material and/or air can be disposed in the gap. The first conductor and the second conductor can have an aspect ratio ranging from approximately 0.1 to 100. The first conductor can be suspended on a surface extending from the second conductor and also be disposed in a gap between the conductors. The first and second conductor can comprise multiple portions, and they can have a height ranging from approximately ten micrometers to approximately 500 micrometers.

The first and the second conductor can also have certain other characteristics in accordance with embodiments of the present invention. For example, the first conductor can be a hot conductor and the second conductor can be a ground conductor to form a waveguide. The waveguide can transmit a data signal, such as a radio frequency signal. The first conductor can having a diameter and the second conductor can having an inner diameter. The ratio of the inner diameter to the diameter can range from approximately one to approximately one and a half. The first conductor and the second conductor can have a polygonal or circular cross section area. The first conductor and the second conductor can be with at least one of copper, gold, silver, nickel, or an alloy. The first conductor and the second conductor have a sidewall surface that is one of a substantially vertical alignment, a substantially horizontal alignment, a sloped alignment, or normal to a substrate surface.

An interconnect fabrication method embodiment according to the present invention can comprise providing a first conductor, providing a second conductor, and disposing the second conductor proximate at least a portion of the first conductor so that first conductor and the second conductor are electrically separated by a gap. The gap can be disposed between the first conductor and the second conductor. A fabrication method can also include aligning the first conductor axis and the second conductor axis in a substantially coaxial alignment such that interconnect is a coaxial interconnect. Still yet, a fabrication method can include providing a gas in the gap such that the gas is located between the first conductor and the second conductor and the gas clads the first conductor. The gas can be air such that the gap consists essentially of air.

Other features of a fabrication method embodiment can include forming at least one of the first conductor and the

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second conductor to have at least one of a polygonal or circular cross sectional shape. In addition, a method can comprise providing at least a portion of one of the first conductor or the second conductor by electroplating at least one of a metal or a metal alloy. Still yet, a method can include forming at least one of the first conductor and the second conductor with multiple portions to provide the first conductor or the second conductor is a composite. The first conductor can be coupled to a hot plane that couples the first conductor to at least one other hot conductor of another interconnect structure, and the second conductor can be coupled to a ground plane so that the second conductor is coupled to at least one other ground conductor of another interconnect. A material can be imprinted, such as by nanoimprinting, to provide a pattern used to form at least one of the first conductor and the second conductor. Also, the first and second conductor can be comprised of isolated detached portions.

In yet another embodiment of the present invention, an integrated system comprising interconnects with multiple conductors, an interconnect structure can comprise a first conductor proximate a substrate. A second conductor can be placed proximate the first conductor such that the second conductor is separated from the first conductor by a gap region disposed between the first conductor and the second conductor. The second conductor can be disposed at least partially above or below the first conductor. The gap region can comprise at least one air gap layered on a second air gap. The first conductor can have an exterior sidewall surface and the second conductor can have an interior sidewall surface. The exterior sidewall surface can be substantially parallel to the interior sidewall surface.

Other embodiments of the present invention can comprise a third conductor. The third conductor can be disposed below the first conductor, and situated proximate the second conductor so that the second and third conductors at least partially surround the first conductor. The first conductor can be suspended on a polymer layer above the substrate and the second conductor is generally disposed around the first conductor. Alternatively, a third conductor can be disposed between the first and second conductors and the first and second conductors can substantially encase the third conductor. The first conductor and the second conductor can be coaxially aligned. Also, the first conductor and the second conductor can have corresponding angular turns such that the first and second conductors form a transmission line to carry a signal from a first component to a second component.

Other aspects and features of embodiments of the present invention will become apparent to those of ordinary skill in the art, upon reviewing the following description of specific, exemplary embodiments of the present invention in conjunction with the accompanying figures.

#### BRIEF DESCRIPTION OF DRAWINGS

FIG. 1 illustrates a cross-sectional view of a micro-strip interconnect structure in accordance with some embodiments of the present invention.

FIG. 2 illustrates a perspective view of two coaxial interconnect structures according to some embodiments of the present invention with FIG. 2A depicting a square coaxial interconnect structure and FIG. 2B depicting a circular coaxial interconnect structure.

FIG. 3 illustrates a perspective view of an array of coaxial interconnect structures fabricated in accordance with some embodiments of the present invention.

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FIG. 4 illustrates a top view of a rectangular coaxial interconnect structure fabricated in accordance with some embodiments of the present invention.

FIG. 5 illustrates a side view of a sloped coaxial interconnect structure fabricated in accordance with some embodiments of the present invention.

FIG. 6 illustrates a cross-sectional view of the sloped coaxial interconnect structure of FIG. 5 fabricated in accordance with some embodiments of the present invention.

FIG. 7 illustrates an interconnect fabrication method according to some embodiments of the present invention with FIGS. 7A-7J showing various stages of such an interconnect fabrication method.

FIG. 8 illustrates a cross-sectional view of another interconnect structure according to the present invention which can be utilized as a transmission line.

FIG. 9 illustrates an interconnect fabrication method according to some embodiments of the present invention with FIGS. 9A-9E showing various stages of such an interconnect fabrication method.

FIG. 10 illustrates a cross-sectional view of an interconnect array according to some embodiments of the present invention.

FIG. 11 illustrates a cross-sectional view of yet another interconnect structure according to some embodiments of the present invention.

FIG. 12 illustrates a cross-sectional view of yet another interconnect structure according to some embodiments of the present invention.

FIGS. 13-14 illustrate cross-sectional views of an interconnect structure fabricated in accordance with some embodiments of the present invention.

FIG. 15 illustrates a top view of a parallel plate interconnect structure and associated probe pads connecting the parallel plate interconnect structure to another component.

FIG. 16 illustrates a perspective view of an interconnect structure fabricated in accordance with some embodiments of the invention that can be used to route radio frequency signals.

#### DETAILED DESCRIPTION OF PREFERRED & ALTERNATIVE EMBODIMENTS

Referring now to the figures, wherein like reference numerals represent like parts throughout the several views, exemplary embodiments of the present invention will be described in detail. Throughout this description, various components may be identified having specific values or parameters, however, these items are provided as exemplary embodiments. Indeed, the exemplary embodiments do not limit the various aspects and concepts of the present invention as many comparable parameters, sizes, ranges, and/or values may be implemented.

The various embodiments of the present invention provide high performance interconnect structures and associated interconnect fabrication methods. Interconnects according to the present invention can be on-chip or off-chip interconnect structures. In addition, interconnects fabricated in accordance with embodiments of the present invention can low loss characteristics and can also be compact interconnects to enable small integrated package sizes. Interconnects fabricated in accordance with embodiments of the present invention can be utilized to route radio frequency (RF) signals such that the frequency of the RF signals need not be adjusted for transmission. Still yet, some interconnect embodiments of the present invention have low inductance values to provide an

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interconnect having low power loss, efficient signal carrying characteristics, and low simultaneous switching noise characteristics.

Some interconnect structures according to the present invention can be fabricated as coaxially-shaped interconnects with an inner conductor and an outer conductor disposed proximate the inner conductor. The two conductors (inner and outer) can be separated by a gap thereby providing ultra-low loss and ultra low permittivity characteristics. Matter can be disposed within the gap such as a gas, solid, or a combination thereof. Alternatively, air can be disposed within the gap to provide an air cladding around an inner conductor.

FIG. 1 illustrates a cross-sectional view of a micro-strip interconnect **100** comprising multiple conductive layers in accordance with some embodiments of the present invention. As shown, the interconnect **100** generally comprises a substrate **105**, a first conductor **110**, and a second conductor **115**. The first conductor **110** is shown disposed on the substrate **105**, and the second conductor **115** is shown disposed within a material, such as a polymer material. The second conductor **115** can be suspended in a material or at least partially disposed with a material. The conductors **105**, **110** can be used to connect electrical components and/or carry data signals, such as RF signals. As an example, the interconnect **100** may be used as a transmission line to connect electrical components on the same integrated chip, the same board, or to connect one chip to another chip. The substrate **105** can comprise organic materials such that the substrate **105** is organic. Other substrate materials can include low cost fiberglass/epoxy substrates based on the resins of tetra-bromo bisphenol A (FR4) and bismaleimide triazine (BT).

As shown, the interconnect **100** is fabricated in a parallel plate arrangement. The two conductors **110**, **115** are electrically isolated from each other with the first conductor **110** being disposed below the second conductor **115**. The two conductors **110**, **115** may have different widths, thickness, or made of different metals. Alternatively, the physical characteristics of the two conductors **110**, **115** may be substantially the same. An advantageous feature of some embodiments of the present invention is the use an air gap or air cladding to separate, at least partially, conductors. Air gap **120** is illustrated in FIG. 1 as isolating the first conductor **110** and the second conductor **115** from each other. Indeed, the air gap **120** separates the first conductor **110** from the second conductor **115**.

While the conductors **110**, **115** of interconnect **100** are fabricated in plates parallel to one another, other transmission line arrangements are also contemplated and possible in accordance with the various embodiments of the present invention. For example, such additional arrangements may include microstrip, co-planar strip line, strip line, rectangular, and coaxial alignment. In addition, the interconnect **100** can be utilized as a horizontal or vertical interconnect structure, or can be fabricated to connect such interconnect structures. Still yet, the interconnect **100** can be fabricated in straight line arrangements, square shaped structures, or to connect interconnects at different vertical levels on multi-layered chips.

FIG. 2 illustrates a perspective view of two coaxial interconnect structures according to some embodiments of the present invention. More specifically, FIG. 2A depicts a square coaxial interconnect structure **200** and FIG. 2B depicts a circular coaxial interconnect structure **250**. As illustrated in FIGS. 2A and 2B, an interconnect device according to the present invention can comprise a first conductor **205**, **255** and a second conductor **210**, **260**. The first conductor **205**, **255** may be an inner conductor and the second conductor **210**, **260** may be an outer conductor or shell conductor in a coaxial

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interconnect device. The first conductor **205**, **250** can define a first conductor axis, and the second conductor **210**, **260** can define a second conductive axis. As illustrated in FIGS. 2A and 2B, the second conductor **210**, **260** is disposed around the first conductor **205**, **255** such that first conductor axis is substantially coaxially aligned with the second conductor axis.

The interconnects **200**, **255** can be fabricated of copper and can be used as chip-to-substrate power and ground connections (or Inputs/Outputs). For example, the first conductors **205**, **255** and the second conductors **210**, **260** in a coaxial configuration can be connected to a power plane and a ground plane, respectively. That is the first conductors **205**, **255** can be coupled together and the second conductors **210**, **260** can be coupled together. The ratio between an inner diameter of the second conductors **210**, **260** and the outer diameter of the inner conductors **205**, **255** can range from approximately one to approximately one and a half. This advantageous feature of embodiments of the present invention enables low parasitic loop inductance relative to conventional technologies.

As shown by interconnects **200**, **250** embodiments of the present invention enable production of circular and non-circular shaped interconnect structures. A square coaxial structure may have a lower parasitic inductance over a circular coaxial structure if the width of the center square equals the diameter of the center pillar in the circular structure with the same gap between the center and the shell.

Variation of the ratio of the physical characteristics of the interconnects **200**, **255** can alter associated inductances. For example, if the ratio between inner conductor thickness to interior width of an outer conductor becomes smaller, a coaxial interconnect can provide an improved and low parasitic inductance. In addition, a square coaxial structure may have a lower parasitic inductance over a circular coaxial structure if the width of an inner square conductor equals the diameter of a center circle conductor in a circular coaxial structure with the same gap distance between the conductors.

FIG. 3 illustrates a perspective view of an array **300** of coaxial interconnect structures fabricated in accordance with some embodiments of the present invention. While certain portions of the discussion herein discuss a particular interconnect, it should be understood that embodiments of the present invention can be utilized to form an interconnect array, such as array **300**. The interconnects discussed herein according to the various embodiments of the present invention can be formed as discussed in greater detail below, and also in accordance with the fabrication methods discussed in U.S. patent application Ser. No. 11/534,668, which is hereby incorporated by reference in its entirety as if fully set forth herein. In addition, the interconnects discussed herein can have physical characteristics similar to the interconnects discussed in this application.

As shown, array **300** consist of multiple interconnects, such as interconnect A. Each of the illustrated interconnects in FIG. 3 have coaxially aligned conductors. Indeed, as shown, each interconnect has a center (or inner) conductor and a shell (or outer) conductor disposed around the center conductor. For example, interconnect A has an inner conductor **305** and an outer conductor **310**. In accordance with some embodiments of the present invention, the center and shell conductors are substantially coaxially aligned. Indeed, inner conductor **305** and outer conductor **310** are substantially coaxially aligned. In other embodiments, the conductors may not be coaxially aligned.

In an array configuration, all of the center conductors of the interconnects may be coupled together and all of the outer conductors of the interconnects may be coupled together.

This coupling can be accomplished with materials beneath the surface upon which the interconnects are disposed upon. For example, one sub surface conductive layer may connect the inner conductors and another sub surface may connect the outer conductors. Other coupling methods in interconnect arrays are also possible in accordance with embodiments of the present invention. Such coupling can enable the interconnects to be utilized as I/O interconnects.

Also as illustrated, the interconnects in array **300** have gap regions defined between the inner and outer conductors. More specifically, with reference to interconnect **A**, a gap region can be defined between an outer surface wall of the center conductor **305** and the interior surface wall of the shell conductor **310**. The gap region can be formed to hold or contain a gas, such as ambient air, or a material can be placed within the gap. For example, a dielectric material or a polymer material may be disposed within the gap region. Based on the application and use of the interconnect array **300**, it may be desirable to leave the gap empty such that ambient air is in the gap or another material or gas is disposed within the gap. In other embodiments a combination of substances may be disposed within the gap region.

The interconnect array **300** can be used to connect (or couple) multiple components. The components can be different devices and alternatively can be different components within an IC packaged device. For example, the interconnect array **300** can be used as interconnect input/output that provide signals and power to a chip. In addition, the interconnects can be used as wave guides to transmit data signals, such as RF signals, from one component to another. Components can include integrated circuits, semiconductor wafers, substrates, or any other items to be electrically connected or coupled. Typically, interconnects connect components by having ends attached, bonded, or coupled to a surface of a component.

As illustrated, the array **300** comprises interconnects all having similar physical characteristics. Such characteristics include height, thickness, interior and exterior diameters, composition, and cross-section geometry. In some embodiments, it may be desirable to vary these characteristics. For example, the center conductors may have a circular cross section and the outer conductor may have a square shaped cross section. Advantages of different geometrical cross sections include the ability to tune a characteristic impedance and design of an interconnect structure for minimized losses or uniform electromagnetic fields. Other varying physical characteristics are also achievable in accordance with other embodiments of the present invention.

FIG. **4** illustrates a top view of a coaxial interconnect structure **400** fabricated in accordance with some embodiments of the present invention. As shown, this interconnect structure **400** is formed with an inner conductor **405** and an outer conductor **410**. The inner conductor **405** is separated from the outer conductor **410** by a gap **415**. Indeed, the gap **415** can encase or surround the inner conductor **405** such that it is electrically separated from the outer conductor **410**. Such separation enables the two conductors **405**, **410** to carry an electrical signal. Also as shown, the inner conductor **405** can be substantially coaxially aligned with the outer conductor **410**.

The inner conductor **405** may be positioned within the outer conductor **410** in various positions in accordance with the embodiments of the present invention. As shown, the inner conductor **405** is separated from the outer conductor **410** at approximately equal distances on each of its exterior sidewall surfaces **A**, **B**, **C**, and **D**. This type of separation may

be desirable in some embodiments and in other embodiments, the separation distances may vary.

Also, the inner conductor **405** can be positioned within the outer conductor **410** so that the conductors have corresponding sidewalls. For example, as shown, the inner conductor **405** has exterior sidewalls and sidewall surfaces **A**, **B**, **C**, and **D**. The sidewall surfaces **A**, **B**, **C**, and **D** can be substantially parallel to the interior sidewalls of the outer conductor **410**. The corresponding sidewalls can be substantially normal to a component on which the interconnect **400** is coupled, or the corresponding sidewalls can also be sloped or angled as shown in FIGS. **5** and **6**.

FIG. **5** illustrates a side view of a sloped coaxial interconnect structure **500** fabricated in accordance with some embodiments of the present invention and FIG. **6** a cross-sectional view of the sloped coaxial interconnect structure **500**. The interconnect structure **500** generally comprises an inner conductor **505**, an outer conductor **510**, and a gap **515** defined by and disposed between the conductors **505**, **510**. The gap can **515** clad the inner conductor **505** and when a gas, such as air, is disposed within the gap **515**, an air cladding is disposed around the inner conductor **505**. Other materials or a combination of materials can also be disclosed within the gap **515**. As FIG. **5** depicts, multiple sloped interconnects can be formed in accordance with embodiments of the present invention to form an array of sloped interconnects.

As is best illustrated in FIG. **6**, the inner conductor **505** and the outer conductor **510** have sloped sidewall surfaces. Indeed, the inner conductor **505** and the outer conductor **510** have an approximate slope angle of 22.5 degrees relative to the surface on which the interconnect structure **500** is disposed upon. Other sloped angles are possible in accordance with embodiments of the present invention. For example, the slope angle can range from approximately 0 to approximately 60 degrees. Also, it is possible to vary the slope angle of the inner conductor **405** and outer conductor **415** such that they have different slope angles. While FIGS. **5** & **6** illustrate a circular cross sectional shaped interconnect having sloped sidewalls, other geometrically shaped cross sections can be fabricated to have sloped sidewalls. For example, an interconnect having an octagonal cross section can be fabricated to have sloped sidewalls.

FIG. **7** illustrates an interconnect fabrication method **700** according to some embodiments of the present invention with FIGS. **7A-7I** showing various stages of such an interconnect fabrication method. A method **700** can comprise creating high-performance interconnects by providing a first conductor, providing a second conductor, and disposing the second conductor around at least a portion of the first conductor to electrically isolate the conductors. A method can also comprise aligning the conductor in a substantially coaxial alignment such that formed interconnect is a coaxial interconnect. A method can also additionally comprise disposing the second conductor proximate at least a portion of the first conductor so that first conductor and the second conductor are electrically separated by a gap disposed between the first conductor and the second conductor and aligning the conductors in a substantially coaxial alignment.

It will be understood that process **700** is only one process implementation embodiment of the present invention and that other process embodiments are also possible. Also, process **700** can be performed in various orders and utilize additional process materials and parameters in fabricating interconnects.

The process **700** can begin by depositing several layers on a surface **705** as shown in FIG. **7A**. The several layers can include a titanium/copper/titanium layer, which can be

deposited to have a 30 nm, 1000 nm, and 10 nm thickness, respectively. Only the copper layer is shown as in FIG. 7A as metal layer **710** (or power plane **710**). The copper layer can be first metallized by DC sputtering on a silicon wafer. The copper metal layer can form a power plane. As will be evidenced by process **700**, the power plane **710** can be coupled to the inner conductors of the formed interconnects. Other metals can be used to form the power plane **710** such as gold, silver, nickel, or other conductive metals.

The process **700** can continue by depositing a layer of silicon dioxide **715** onto the metal layer **710**. The silicon dioxide layer can be approximately 1.5 micrometers thick. The silicon dioxide layer **715** can be deposited on the metal layer **710** by plasma enhanced chemical vapor deposition (PECVD) at approximately 250° C. A photoresist, such as Microposit SC1813 photoresist (Shipley Corporation), can then be applied on the silicon dioxide **715**. The photo resist can then be photo-patterned, and Buffered Oxide Etch (BOE) can be used to etch the silicon dioxide and titanium layers in the exposed, patterned areas. Any remaining photoresist can be removed with acetone.

This patterning and etching forms apertures **717**. The apertures provide access to the metal layer **720** as shown in FIG. 7A. Next, a metal can be deposited in the apertures **717** to fill the apertures also as shown in 7A. For example, copper can be electroplated to fill the apertures **717** in the silicon dioxide layer.

The process then continues as shown in FIG. 7B. At this point in the process, a second metal layer **725** can be deposited. This metal layer **725** can form a ground plane. The ground plane can be used to couple the outer conductors of the resulting formed interconnects. An adhesive metal such as titanium may also be applied with the second metal layer **725** for adhesive purposes. For example, the metal layer **725** can be a layer of copper and the adhesive layer can be a layer of titanium. These metals can be sputtered to form the metal layer, the copper can have a thickness of approximately of 1000 nm, and the titanium can have a thickness of approximately 10 nm. Other metal types and thicknesses are also possible in accordance with additional embodiments of the present invention.

Then, a second silicon dioxide layer **730** can be deposited. The second silicon dioxide layer **730** can be photo-patterned to form additional apertures **727** as shown in FIG. 7C. These apertures **727** can form the base mold to assist in forming a shell conductor in the resulting coaxial interconnects. As shown in FIG. 7C, these apertures can be formed as circular rings around the electroplated copper pillars **720**. Next as shown in FIG. 7D, the second metal layer **725** can be etched to isolate the first metal layer **710** (or power plane **710**) from the second metal layer **725** (or ground plane **720**). And, the silicon dioxide layer on top of the second metal layer **730** can be removed to expose formed copper pillars and annular rings as shown in FIG. 7E.

The process **700** then continues at FIG. 7F, when a polymer layer **735** can then be applied. The polymer layer **735** can be a thick layer of Avatrel 2195P (available from Promerus LLC in Brecksville, Ohio), and it can be spun on top of the patterned silicon dioxide layer **730**. FIG. 7G shows the polymer layer **735** after being applied. The spin rate of the polymer can be approximately 500 rpm for approximately 60 seconds. Then the polymer can be softbaked for approximately 30 minutes softbake on a hotplate at 100° C. Then about an 250 mJ/cm<sup>2</sup> UV exposure dose can be performed (365 nm irradiation). Following the exposure, a 20 min. post exposure bake at approximately 100° C. can be done followed by

ultrasonic developing to produce hollow-core coaxial polymer plating molds **737** as shown in FIG. 7G.

Metal can then be deposited in the molds **737** to form metal pillars **740** as shown in FIG. 7H. For example, the metal pillars **740** can be formed by electroplate deposition of copper. The electroplating solution can comprise 0.5 M H<sub>2</sub>SO<sub>4</sub>, 0.5 M CuSO<sub>4</sub>, 0.25 M brightener and 0.25 M carrier. Next, an adhesive **745**, such as tin-lead solder (e.g., approximately 5 micrometer layer of Sn—Pb (60/40) solder), can be applied onto the metal pillars **740** as shown in FIG. 7H. Then the pillars **740** can be bonded with another copper surface **750** with an approximately 5 micrometer thick Sn—Pb (60/40) solder layer, which was electroplated on top of the copper coaxial structure as shown in FIG. 7J. The copper surface **750** can also be coupled to another component such as component **755**.

FIG. **8** illustrates a cross-sectional view of two coaxial interconnect structures **800**, **850** according to the present invention. The interconnect structures **800**, **850** can be utilized as a transmission line to provide an electronic signal from one component to another component. The components may be located on the same substrate, on different substrates, or on different levels on a multilayered integrated package.

As shown, the interconnect structures **800**, **850** generally comprises multiple conductors. These conductors can include bottom conductor **805**, middle conductor **810**, and outer conductor **815**. Likewise, the interconnect structure **850** generally comprises multiple conductors. These conductors can include bottom conductor **855**, middle conductor **860**, and outer conductor **865**. The multiple conductors of each interconnect **800**, **850** can be formed in portions or have different segments. The segments may or may not physically contact each other.

The interconnect structures **800**, **850** can be fabricated in a parallel plate arrangement and have a suspended ground microstrip configuration. Indeed as shown, the middle conductors **810**, **860** are suspended above the bottom conductors **805**, **855**. The microstrips (or middle conductors **810**, **860**) can also be suspended above an organic substrate **801**, such as FR4 or BT substrates. Also as shown, multiple interconnects **800** and **850** can be constructed on the same substrate **825** to transmit multiple signals. While the interconnects **800**, **820** are illustrated on the same substrate level, they can be fabricated in a stacked alignment according to some embodiments of the present invention.

The interconnect structures **800**, **850** also generally comprises gap regions **820**, **870**. The gap regions **820**, **870** separates the conductors from each other. Air can be disposed within the gap region **820**, **870** so that the interconnect structure can be a low-loss transmission line having air-cladding disposed around the middle conductors **810**, **860**. The gap region **820**, **870** can include layered gaps. The layered gaps can be separated by a dividing material, such as a layer of polymer material. Advantageously, the gapped interconnect structure **800**, **850** can provide a low effective dielectric constant and dissipation factor thereby resulting in lower attenuation and phase loss associated with the interconnect structure **800**, **850**. Thus, interconnects **800**, **850** can be used for high frequency interchip communication with essentially zero dielectric loss and reduced conductor loss. Multilevel signaling techniques can be combined with the interconnects **800**, **850** to achieve high data rates over long traces with low insertion loss. Shown below the interconnects **800**, **850** in FIG. **8** are schematic representations of the coaxial alignment possible in accordance this embodiment of the present invention. As shown, an inner conductor (such as middle conductors **810**, **860**) are coaxially aligned with outer conductors



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(such as the bottom conductors **850**, **855** and outer conductors **815**, **865**) of interconnects **800**, **850**.

FIG. **9** illustrates an interconnect fabrication method according to some embodiments of the present invention with FIGS. **9A-9E** showing various stages of such an interconnect fabrication method. Air-insulated parallel plate and suspended ground microstrip lines can be created on organic substrates using CMOS-compatible processing techniques and sacrificial polymer. In general, a copper signal line can be etched with a sacrificial polymer layer defined around it and the polymer is then covered with an overcoat and an electroplated ground line.

The fabrication process **900** is in general a build up process. As shown in FIG. **9A**, the process initiates by depositing a metal layer **905** on a substrate **900**. The substrate can be an organic substrate such as FR4 or BT. The metal can be copper and be deposited to have a thickness of approximately 27 micrometers. After being deposited, the metal layer **905** can be patterned using and developed to form multiple metal segments **905** such as shown in FIG. **9A**. The photoresist can be AZ4620 from Clariant and can be spun to a thickness of approximately 10 micrometers. The photoresist can be soft-baked at approximately 110° C. for approximately 10 minutes. The photoresist can be photopatterned and the metal layer can be etched and divided into segments have a width of approximately 220 micrometers. For example, the metal layer can be etched with a solution of approximately 15% H<sub>2</sub>O<sub>2</sub> and approximately 5% H<sub>2</sub>SO<sub>4</sub>. The applied photoresist can then be stripped, leaving only the metal layer segments to form signal lines as shown in FIG. **9A**.

A sacrificial polymer layer **910** can then be disposed onto the metal layer segments **905**. The polymer can be a photo-sensitive sacrificial polymer, such as Unity 2203P from Promerus, LLC (Brecksville, Ohio). The polymer layer **910** can be spun onto the metal layer segments to have a thickness of approximately fifteen micrometers. The polymer layer **910** can then be soft-baked for approximately ten minutes then photodefined and developed on a hot plate. The hot plate can have a temperature of approximately 110° C. for approximately 10 minutes. Then the polymer layer **910** can then be rinsed with isopropyl alcohol, leaving portions of the polymer material **910** over the metal layer segments. The polymer material portions **910** can have approximately a 600 micrometer wide encapsulation regions over the metal layer segments **905** as shown in FIG. **9B**.

Next, a dielectric material **915** can be provided on the polymer material **910** as illustrated in FIG. **9C**. The dielectric material **915** can be Avatrel 2000P dielectric polymer, and it can be spun onto at a thickness of approximately 20 micrometers over the encapsulated metal layer segments **905**. The Avatrel can be dosed with approximately 200 mJ/cm<sup>2</sup> ( $\lambda=365$  nm) and developed to define regions allowing access to the probe pads. An electroplating seed layer **920**, such as titanium/copper/titanium can then be applied onto the dielectric material **915** to overcoat the dielectric material **915**. The thickness of the seed layer can be approximately 150 angstroms for the titanium and approximately 1000 angstroms for the copper. The titanium layer can be used to increase adhesive characteristics of the copper.

After this, a second metal layer **925** can then be applied to form ground lines. The second metal layer **925** can be electroplated to a thickness of approximate 20 micrometers and the photoresist can be stripped. The second metal layer **920** can be a layer of copper and can form several segments of copper **920** as shown in FIG. **9D**. The copper can be etched away with a solution of approximately 7.5% H<sub>2</sub>O<sub>2</sub> and

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approximately 5% H<sub>2</sub>SO<sub>4</sub>. After etching the copper ground lines, FIG. **9D** illustrates the fabrication process at this stage.

In a next stage, a polymer overcoat (not shown) can be applied onto the second metal layer **925**. Then, the overcoat layer can then be defined as needed. For example, a photoresist can be applied to the overcoat layer. The photoresist can be AZ4620 and it can be spun to a thickness of approximately 10 micrometers. Then the photoresist can be exposed to define an electroplating mask for ground lines of three different widths. For example, the widths can be approximately 150 micrometers, 220 micrometers, and 650 micrometers.

Next, the titanium layer can be removed with a buffered oxide etch (BOE) solution. The polymer overcoat can be cured in a nitrogen purged tube furnace heated to approximately 180° C. for approximately 2 hours. The furnace temperature can have a ramp rate of approximately 3° C./min from 25° C. to 150° C. and approximately 1° C./min from 150° C. to 180° C. The polymer can be cured and also the sacrificial layer **910** can be decomposed. Holes or perforations can be made in the polymer overcoat to enable gases from the decomposition of the encapsulated sacrificial layer **910** to permeate through the polymer overcoat. After fully decomposing, the sacrificial layer **910** is removed to form a gap **930** that separates the metal layer segments **905** and **925**.

FIGS. **10-12** illustrate other types of interconnect structures that can be fabricated in accordance with various embodiments of the present invention. FIG. **10** illustrates a cross-sectional view of an interconnect array **1000** having interconnect structures in which a first conductor is suspended above a second conductor. While the interconnect array **1000** is shown on the same substrate **1001**, the interconnect array **1000** can consist of interconnect structures (or transmission lines) on various layers of a multilayer integrated package in other embodiments of the present invention.

The interconnect array **1000** can be used as an array of transmission lines to carry data signals. For example, consider interconnect **1005**. As shown interconnect **1005** generally comprises a first conductor **1010** suspended above a second conductor **1015**. Advantageously, the suspension of one conductor over another according to this and other embodiments of the present invention can enable a dielectric constant close to that of free space. The first conductor **1010** can be a ground strip and the second conductor **1015** can be a hot (or power) strip in accordance with some embodiments of the present invention.

As shown, the first conductor **1010** and the second conductor **1015** are separated by a gap region **1020**. The gap region **1020** can be formed by decomposing a sacrificial material (not shown). Also, the gap region **1020** can be a void region such that it is filled with a gas, such as ambient air. Also, other materials can be disposed within the gap region **1020**. For example, polymer and foam materials are examples of other materials. Still yet, a combination of a gas and a solid substance may be disposed within the gap region **1020**.

An overcoat layer **1025** is also shown in FIG. **10**. The overcoat layer **1025** may be disposed on the first conductor **1010** as shown. As mentioned above, the overcoat layer **1025** can enable the suspension of the first conductor **1010** over the second conductor **1015**. For example, after application of the overcoat layer **1025**, holes or other perforations (not shown) may be made in the overcoat layer **1025**. These holes or perforations can enable the escape of gaseous decomposition products that can originate during decomposition of a sacrificial polymer.

After decomposing a sacrificial layer to remove it, the first conductor **1010** can be at least partially disposed within the

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overcoat layer **1025** such that it is suspended above the second conductor **1015**. Suspension of the first conductor **1010** can occur in many fashions. For example, a suspended conductor may be deposited on a polymer layer or can be disposed within a polymer layer. Alternatively, a metal overcoat layer may be deposited on a polymer layer such that the metal overcoat layer and the polymer layer encase another conductor.

FIG. **11** illustrates a cross-sectional view of additional interconnects **1100**, **1150** according to some embodiments of the present invention. As shown the interconnects **1100**, **1150** are disposed proximate a substrate **1101** and both generally comprise at least one conductor suspended above another conductor. More specifically, interconnect **1100** generally comprises a first conductor **1105**, a second conductor **1110**, and a third conductor **1115**. As shown, the second conductor **1110** is suspended above the first conductor **1105**, and the third conductor **1115** is suspended above the second conductor **1105**. The first and third conductors **1105**, **1115** may be disposed around the second conductor **1110**. That is, the first and third conductors **1105**, **1115** can form an outer shell around the second conductor **1110**. In this arrangement the three conductors can be situated in a substantially coaxial alignment wherein the first and third conductors **1105**, **1115** form an outer shell that is coaxial with the second conductor **1110**.

The interconnect **1100** also generally comprises multiple suspension layers and air gaps. For example, the interconnect **1100** can include multiple suspension layers such as suspension layers **1107**, **1113**. The suspension layers **1107**, **1113** can be a material capable of holding or suspending a conductor. For example, the suspension layers **1107**, **1113** can be a polymer material. Suspension layer **1107** is shown as suspending the second conductor **1110** above the first conductor, and the suspension layer **1113** suspends the third conductor **1115** partially above the first and second conductors **1105**, **1110**.

The interconnect **1100** can also generally include a gap region. The gap region can comprise multiple gap spaces such as a first gap **1120** and a second gap **1125**. The gaps **1120**, **1125** can be formed by decomposing a sacrificial material. The gaps **1120**, **1125** can be positioned in a stacked or layered alignment. For example, as shown, the second gap **1125** is positioned above the first gap **1120**. A dividing material, such as suspension layer **1107** can segment the gap region into the multiple gap spaces, such as the first gap **1120** and the second gap **1125**.

According to the various embodiments of the present invention, various materials may be disposed within the first gap **1120** and the second gap **1125**. For example, in some embodiments, a gas such as air may be disposed in both the first gap **1120** and the second gap **1125**. In this exemplary embodiment, the air gaps provide an air cladding around the second conductor **1110**. This air cladding separates the second conductor **1110** from the first and third conductor **1105**, **1115**. Alternatively, other materials such a solid or solid/gas combination may be disposed within the gaps **1120**, **1125**. For example, a polymer/air combination or a foam material (i.e., gas in solid matrix) may be disposed in the gaps **1120**, **1125**.

The other interconnect, interconnect **1150**, illustrated in FIG. **11** has certain similar features relative to interconnect **1100**. Indeed, interconnect **1150** generally comprises at least one conductor at least partially suspended above another conductor. For example, a second conductor **1160** and a third conductor **1165** are suspended above a first conductor **1155**, and a fourth conductor **1170** is suspended partially above the first, second, and third conductors **1155**, **1160**, and **1165**.

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As shown, the second and third conductors **1160**, and **1165** are two independent conductors according to other advantageous embodiments of the present invention. These dual conductors can enable transmission of multiple data signals by interconnect **1150** in a transmission line embodiment. In other embodiments, more than two signal carrying conductors can be utilized.

The interconnect **1150** may also comprise a gap region and suspension materials. The gap regions can be stacked or layered such as a first gap **1175** being stacked on a second gap **1180**. The two gaps **1175**, **1180** can encase or surround the second and third conductors **1160**, **1165**. This enables a substance or material that is disposed in the gaps **1175**, **1180** to clad the second and third conductors **1160**, **1165**. For example, if air is disposed within the gaps **1175**, **1180** then an air cladding can be disposed generally around the second and third conductors **1160**, **1165**.

FIG. **12** illustrates a cross-sectional view of yet another coaxial interconnect **1200** according to some embodiments of the present invention. This interconnect **1200** is generally comprised of multiple conductors and multiple insulation layers disposed on a substrate **1201**. The conductors can be various metal conductive materials and the insulation layers can be various insulating materials, including a polymer material. Interconnect **1200** (as well as the certain other embodiments of the present invention) can be fabricated using nanoimprinting techniques in which a pattern is formed into resist and then additional materials are deposited and layered on the pattern. It should be understood that while interconnect **1200** is shown a single layer interconnect that in accordance with some embodiments of the present invention, the single layer interconnect **1200** can be layered on another interconnect to create a multiple layered interconnect. A multiple layered interconnect can be fabricated using based on imprint techniques such as nanoimprinting. For example, two halves of an interconnect could be fabricated and then bonded together to create a fully coaxial built up structure.

More particularly, and as shown, the interconnect **1200** comprises a first insulation layer **1205**, a first conductor **1210**, a second insulation layer **1215**, a third conductor **1220**, a third insulation layer **1225**, and third conductor **1230**. The first conductor **1210** can be disposed in a portion of the first insulation layer **1205**, and the second isolation layer **1215** and the third isolation layer **1225** can be disposed between the first conductor **1210** and the third conductor **1230**.

The second conductor **1220** can be positioned between the first conductor **1210** and the third conductor **1230**. Indeed, as shown, the second conductor **1220** can be positioned on the second insulation layer **1215** such that it is suspended above the first conductor **1210** and the suspended below third conductor **1230**. The first conductor **1210** and the third conductor **1230** can be electrically coupled together to form an outer shell having multiple detached portions or segments. The outer shell can be disposed around the second conductor **1220** in a substantially coaxial alignment such that the outer shell is situated substantially coaxially with the second conductor **1220**. Such placement of the outer shell (first conductor **1210** and the third conductor **1230**) enables the interconnect **1200** to be used as a transmission line that can carry an electronic signal from one component to another component.

The shell conductor formed by the detached portions (first conductor **1210** and the third conductor **1230**) can also be formed with a continuous metal layer. In certain situations it may be desirable to form a continuous outer shell conductor. In addition, the outer shell conductor can also be perforated to

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enable the escape of gaseous decomposition products from a sacrificial polymer that is used to in forming a gap to separate two or more conductors.

The interconnect **1200** can also generally comprise multiple gap areas. For example, in this particular exemplary embodiment of the present invention, the second conductor **1220** can be disposed within a gap area. The gap area can comprise multiple gap regions, such as a first gap region **1235** and a second gap region **1240**. The gap area can clad the second conductor **1220** such that any substance disposed within the first gap region **1235** and the second gap region **1240** can be disposed around the second conductor **1220**. The gap area can also be divided by a divider that defines the first and second gap regions **1235**, **1240**. For example, and as illustrated in FIG. **12**, the second insulator **1215** extends into the gap area and divides the gap area into the first gap region **1235** and the second gap region **1240**. The gap regions **1235**, **1240** can have the same internal volume in certain embodiments or have different internal volumes in other embodiments.

FIGS. **13-14** illustrate cross-sectional views of another interconnect structure **1300** fabricated in accordance with some embodiments of the present invention. As shown, a narrow ground microstrip line **1305** is shown suspended above a second conductor **1310** to form the parallel plate interconnect **1300**. The parallel plate interconnect can be formed on a substrate, such as substrate **1301**. As can be seen by comparing FIG. **1** and FIGS. **13-14**, this parallel plate interconnect structure **1300** is similar to the interconnect depicted in FIG. **1**. In FIG. **14**, the inventors peeled back or removed a portion of the ground microstrip line **1305** to further study the interconnect structure **1300**.

The parallel plate interconnect **1300** can also comprise additional components. Indeed, the ground microstrip line **1305** is disposed on a layer of polymer material **1303** such that the polymer material **1303** acts a suspension layer to suspend the ground microstrip line **1305** above the second conductor **1310**. Also as shown, the ground microstrip line **1305** and the second conductor **1310** define a gap **1315** between them.

The interconnect structure **1300** shown in FIGS. **13-14** is a sample interconnect embodiment that the inventors fabricated. In this particular interconnect **1300**, the inventors fabricated its components to have certain physical dimensions. For example, the ground microstrip line **1305** has a width of approximately 231 micrometers and the second conductor **1310** has a width of approximately 219 micrometers. Also, the thickness of the suspension polymer layer **1303** is approximately 16 micrometers, the gap **1315** has a height of approximately 15 micrometers between the polymer layer **1303** and the second conductor **1310**, and the second conductor **1310** has a thickness of approximately 17 micrometers. These physical dimensions are exemplary and others are possible in accordance with the various embodiments of the present invention.

FIG. **15** illustrates a top view of an interconnect structure **1500** and associated probe pad array **1505**. The interconnect **1500** can be a parallel plate interconnect similar to that shown in FIGS. **13-14** and can comprise a first conductor **1505** and a second conductor **1510**. The first conductor **1505** can be suspended above the second conductor **1510** such that the conductors **1505**, **1510** are separated from each other. For example, the conductors **1505**, **1510** may define a gap between each other and the gap may consist essentially of air so that the first conductor **1505** is cladded by air.

The probe pad array **1505** can comprise multiple probes. For example, the multiple probes can include a first probe

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**1555**, a second probe **1560**, and a third probe **1565**. The probe pad array **1505** (and the multiple probes **1555**, **1560**, **1565**) enables the interconnect **1500** to be connected to another component. As shown, the multiple probes **1555**, **1560**, **1565** are arranged in a fan out arrangement. The first and third probes **1555**, **1565** may be used to couple another component to the second conductor **1510** and the second probe **1560** may be used to couple the first conductor to another component. It should be understood that other types of probe pad arrays can be utilized in accordance with the embodiments of the present invention.

FIG. **16** illustrates a perspective view of an interconnect **1600** fabricated in accordance with some embodiments of the invention that can be used to route radio frequency signals. As illustrated, the interconnect **1600** has an outer shell conductor **1602** and an inner conductor **1603**. The outer shell conductor **1602** and the inner conductor **1603** can be aligned in substantially coaxial alignment according to some embodiments of the present invention. Also the outer shell conductor **1602** and the inner conductor **1603** can define an air cladding that is disposed between the outer shell conductor **1602** and the inner conductor **1603**.

Generally shown in FIG. **16** is a chip **1605** connected proximate a circuit board (or substrate) **1610**. The chip **1605** and the board **1610** define a gap **1615** situated between the chip **1605** and the board **1610**. The interconnect **1600** can be positioned within the gap **1615** to connect the chip **1605** and the board **1615**.

This interconnect embodiment **1600** can be fabricated to have multiple vertical and multiple horizontal segments. For example, and as shown, the interconnect **1600** has a first horizontal segment V, a second horizontal segment X, and a third horizontal segment Z. The interconnect **1600** can also have a first vertical segment W and a second vertical segment Y. The horizontal and vertical segments enable the interconnect **1600** to route an electrical signal via the outer shell conductor **1602** and the inner conductor **1603**, such as an RF signal, between components, such as the chip **1605** and the board.

The segments V-Z of the interconnect **1600** can be joined together to have corresponding angular turns A-D. At these angular turns the sidewall surfaces of the outer shell conductor **1602** and the inner conductor **1603** can have corresponding angular turns as depicted in FIG. **16**. While shown as approximately 90 degree turns in FIG. **16**, other angular turns are also achievable in accordance with other embodiments of the present invention.

The embodiments of the present invention are not limited to the particular formulations, process steps, and materials disclosed herein as such formulations, process steps, and materials may vary somewhat. Moreover, the terminology employed herein is used for the purpose of describing exemplary embodiments only and the terminology is not intended to be limiting since the scope of the various embodiments of the present invention will be limited only by the appended claims and equivalents thereof. For example, temperature and pressure parameters may vary depending on the particular materials used.

Therefore, while embodiments of this invention have been described in detail with particular reference to exemplary embodiments, those skilled in the art will understand that variations and modifications can be effected within the scope of the invention as defined in the appended claims. Accordingly, the scope of the various embodiments of the present invention should not be limited to the above discussed embodiments, and should only be defined by the following claims and all equivalents.

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We claim:

1. An integrated circuit interconnect structure, the structure comprising:

- a first conductor of an interconnect;
- a second conductor of an interconnect;
- a first layer of suspension material that defines a first gap in a region disposed below the first layer of suspension material; and
- a second layer of suspension material stacked on the first layer of suspension material, the second layer of suspension material defining a second gap stacked above the first gap, and

wherein the second gap is enclosed by the second layer of suspension material and the first layer of suspension material; and

wherein the first conductor and the second conductor are contained within at least one of the first gap and the second gap and are spaced apart from each other in the first gap or the second gap.

2. The integrated circuit interconnect structure of claim 1, further comprising an outer conductor disposed at least partially around the first and second layers of suspension material.

3. The integrated circuit interconnect structure of claim 1, wherein the first conductor and the second conductor are independent conductors configured to carry multiple data signals.

4. The integrated circuit interconnect structure of claim 1, wherein the first gap and the second gap comprise air.

5. The integrated circuit interconnect structure of claim 1, further comprising a third conductor generally placed around the first and second layers of suspension material and a fourth conductor disposed below the first layer of suspension material such that the third and fourth conductors form an outer shell.

6. An integrated circuit interconnect structure, the structure comprising:

- a first layer of suspension material placed on a substrate, the first layer of suspension material defining a first gap between an underside of the first layer of suspension material and the substrate;

- a second layer of suspension material stacked on the first layer of suspension material, the second layer of suspension material defining a second gap disposed between an underside of the second layer of suspension material and a topside of the first layer of suspension material; and wherein the second gap is enclosed by the second layer of suspension material and the first layer of suspension material; and

a pair of independent, spaced apart conductors disposed on at least one of the top side of the first layer of suspension material in the second gap such the spaced apart conductors are co-located in the second gap or in the first gap below the first layer of suspension material such that the spaced apart conductors are co-located in the first gap.

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7. The integrated circuit interconnect structure of claim 6, further comprising an outer conductor disposed on exterior edges of the first and second layers of suspension material such that the outer conductor is located outside of the first and second gaps.

8. The integrated circuit interconnect structure of claim 6, wherein the first and second gaps comprise air.

9. The integrated circuit interconnect structure of claim 6 further comprising an outer shell that is situated in coaxial arrangement with the pair of independent, spaced apart conductors, the outer shell comprising a first outer conductor disposed on the external edges of the first and second layers of suspension material and a second outer conductor disposed below the first gap, the second outer conductor being spaced apart from the first outer conductor by the first layer of suspension material.

10. The integrated circuit interconnect structure of claim 6, wherein the second gap encases the pair of independent, spaced apart conductors when said conductors are disposed on the top side of the first layer of suspension material.

11. An integrated circuit interconnect structure, the structure comprising:

- a first conductor of an interconnect spaced apart from a second conductor of an interconnect, the first conductor and the second conductor having different electrical potential such that the conductors are independent conductors; and

- a layer of suspension material arranged to segment a gap region of the interconnect into an upper gap region and a lower gap region, wherein the upper gap region is disposed to be stacked on the lower gap region, and wherein the upper gap region defines a first enclosed volume that is enclosed off from the lower gap region by the layer of suspension material and the lower gap region defines a second enclosed volume that is enclosed off from the upper gap region by the layer of suspension material,

and wherein the first conductor and the second conductor are co-located and disposed in at least one of the upper gap region and the lower gap region.

12. The integrated circuit interconnect structure of claim 11, wherein the lower gap region and the upper gap region comprise air, and the air in the being disposed between the first conductor and the second conductor.

13. The integrated circuit interconnect structure of claim 11, further comprising a second layer of suspension material stacked on the layer of suspension material, the second layer of suspension material defining the upper gap region.

14. The integrated circuit interconnect structure of claim 11, wherein the first conductor and the second conductor are configured to carry multiple data signals.

15. The integrated circuit interconnect structure of claim 11, further comprising an outer shell that surrounds and encases the upper and lower gap regions.

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